

# 2SB1172, 2SB1172A

## Silicon PNP epitaxial planar type

For low-frequency power amplification

Complementary to 2SD1742, 2SD742A

### ■ Features

- High forward current transfer ratio  $h_{FE}$  which has satisfactory linearity
- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- I type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment

### ■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	-60	V
		-80	
Collector-emitter voltage (Base open)	$V_{CEO}$	-60	V
		-80	
Emitter-base voltage (Collector open)	$V_{EBO}$	-5	V
Collector current	$I_C$	-3	A
Peak collector current	$I_{CP}$	-5	A
Collector power dissipation	$P_C$	15	W
$T_a = 25^\circ\text{C}$		1.3	
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

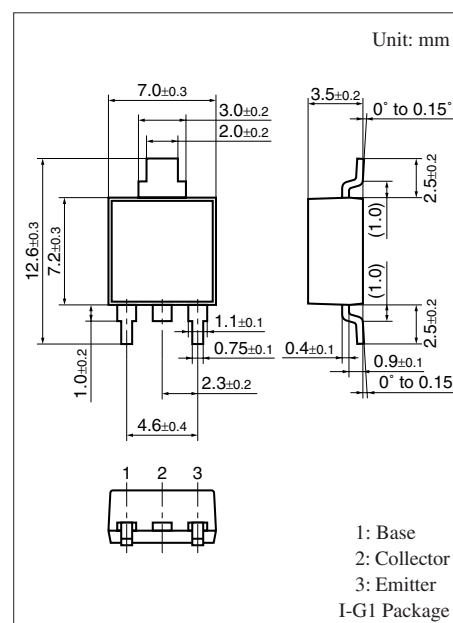
### ■ Electrical Characteristics $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = -30\text{ mA}, I_B = 0$	-60			V
			-80			
Base-emitter voltage	$V_{BE}$	$V_{CE} = -4\text{ V}, I_C = -3\text{ A}$			-1.8	V
Collector-emitter cutoff current (E-B short)	$I_{CES}$	$V_{CE} = -60\text{ V}, V_{BE} = 0$			-200	$\mu\text{A}$
		$V_{CE} = -80\text{ V}, V_{BE} = 0$			-200	
Collector-emitter cutoff current (Emitter open)	$I_{CEO}$	$V_{CE} = -30\text{ V}, I_B = 0$			-300	$\mu\text{A}$
		$V_{CE} = -60\text{ V}, I_B = 0$			-300	
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = -5\text{ V}, I_C = 0$			-1	mA
Forward current transfer ratio	$h_{FE1}^*$	$V_{CE} = -4\text{ V}, I_C = -1\text{ A}$	70		250	—
	$h_{FE2}$	$V_{CE} = -4\text{ V}, I_C = -3\text{ A}$	10			
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -3\text{ A}, I_B = -0.375\text{ A}$			-1.2	V
Transition frequency	$f_T$	$V_{CE} = -10\text{ V}, I_C = -0.5\text{ A}, f = 10\text{ MHz}$		30		MHz
Turn-on time	$t_{on}$	$I_C = -1\text{ A}, I_{B1} = -0.1\text{ A}, I_{B2} = 0.1\text{ A}$		0.5		$\mu\text{s}$
Storage time	$t_{stg}$	$V_{CC} = -50\text{ V}$		1.2		$\mu\text{s}$
Fall time	$t_f$			0.3		$\mu\text{s}$

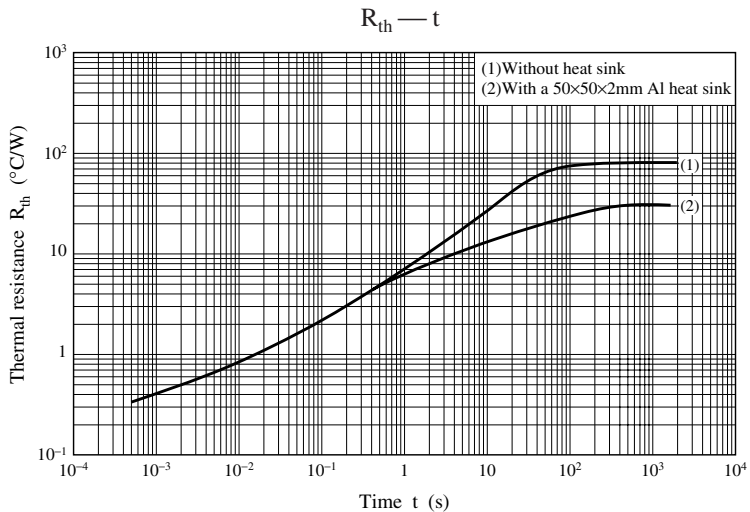
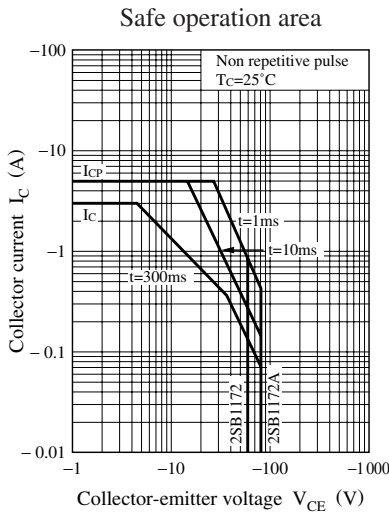
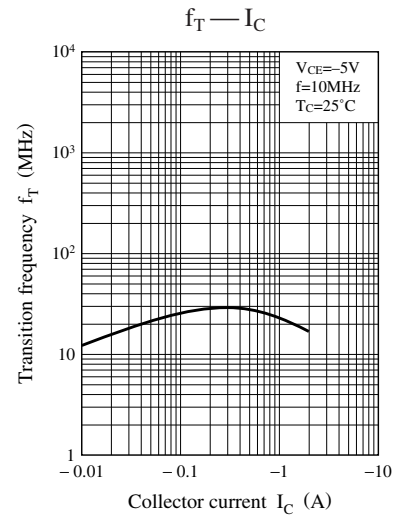
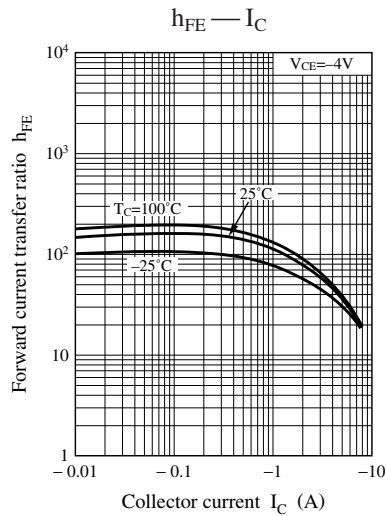
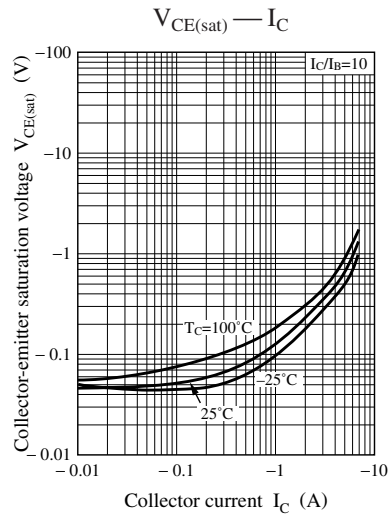
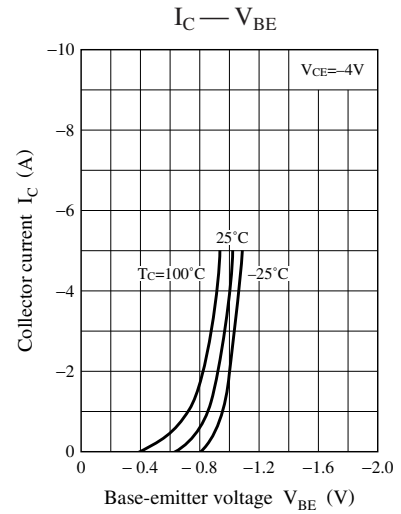
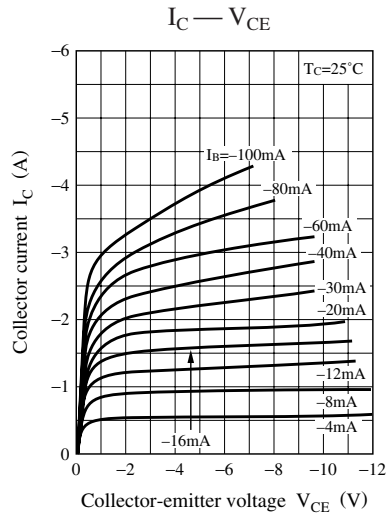
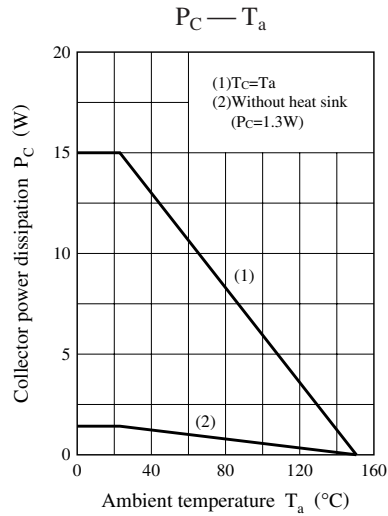
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*: Rank classification

Rank	Q	P
$h_{FE2}$	70 to 150	120 to 250



Note) Self-supported type package is also prepared.



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